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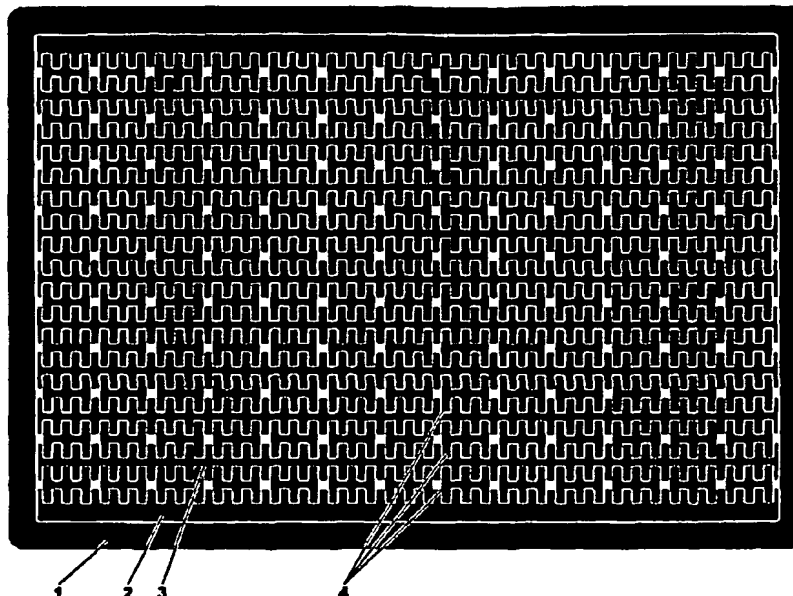
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(54) Title: **SENSOR FOR CAPACITIVE TOUCH PAD POINTING DEVICE**



Artwork for the First (Top) Copper Layer

(57) Abstract: The topology and the shape of sensing electrodes (4, 31) on the Capacity Touch Pad Sensor that allow sensing of small targets are disclosed. Sensor construction utilizes common PCB manufacture technique.